

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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# PARAMETERS

Category:

**VFQFPN** Package NA Speed Temperature 1.8 V Voltage **CPU Manufacturer** Intel® Chipset 910 Yellow Cover Spec. Embedded Core Supply Voltage 3.3 V (VDD) Input Style XTAL Output Style TYPE-SR **Output Supply** 1.05-3.3 Voltage (VDDO) Temp. Grade Suggested - Pkg. Voltage

#### **PACKAGE**

Package	VFQFPN 72 (NLG72)
Description	VFQFP-N 10.0 X 10.0 X 0.9 MM - NO LEAD
Status	Active
Class	PLASTIC
Category	Green
Pb (Lead) Free	Yes
Pb Free Category	e3 Sn
Mark	K
Package Type	VFQFPN
Lead Count	72
Length	10.0 mm
Width	10.0 mm
Thickness	1.0 mm
Pitch	0.5 mm
Tube / Tray	TRAY
Quantity per Tube/Tray	168
Quantity per Reel	1000
Moisture Sensitivity Level (MSL)	3
Moisture Exposure Floor Life	168hrs@<30C/60% RH
Peak Reflow Temperature	260°C
Rebake Conditions	48hrs@125C
Related Package Documents	view documents

## **DOCUMENTS**

 Type
 Title
 Size
 Revision Date

 Product Change Notice
 PCN#: A0808-02R2 ALTERNATE ASSEMBLY LOCATION FOR VFQFP-N-64 AND VFQFP-N-72
 2259 KB
 08/26/2010

 PCN#: TB0909-03 Changed of Moisture Barrier Bag for Tape & Reel Packing
 1133 KB
 10/05/2009

 PCN#: A0903-04 Chipmos Taiwan & Carsem Malaysia as Alternate Assembly Site for Copper Wire Process
 101 KB
 05/12/2009

 PCN#: A0808-02 ALTERNATE ASSEMBLY LOCATION FOR VFQFP-N-64 AND VFQFP-N-72
 129 KB
 08/27/2008

PCN# : A0808-02 ALTERNATE ASSEMBLY LOCATION FOR VFQFP-N-64 AND VFQFP-N-72 129 KB 08/27/2008 PCN# : TB0807-01 Reel Quantity Change on VFQFP-N-68, VFQFP-N-72 56 KB 07/10/2008

#### **DISTRIBUTOR INVENTORY**

Part Distributor Qty Date RFQ Order

No matches found.

## CONTACTS

Sales Offices

> Sales Offices and authorized distributors

Technical Support Clock Help

➤ WWW: Clock Help

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